

4500 Series Ball Bonders

Digital/Analog Systems





The precision and reliability of full automation.

4500 Series Features

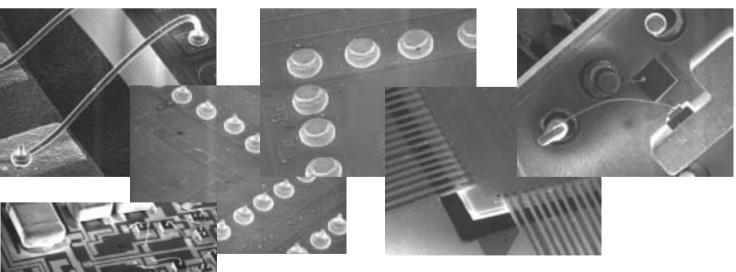
- Consistent ball size via Negative Electronic Flame-Off
- Missing ball detection and auto-stop
- Large 6" x 6" bonding area
- Consistent tail length with fine adjustment on operator panel
- · Deep access capability (optional)
- Z axis DC servo motion with closedloop control
- Phase Locked Loop (PLL) ultrasonic generator and high-Q transducer
- Built-in temperature controller
- Leica™ microscope and spotlight targeting options available
- Ergonomic design with choice of left or right-hand mouse

For process development, production, research or added manufacturing support, the versatile 4500 Series Manual Ball Bonding Systems provide the high yield and excellent repeatability needed for every gold ball bonding application, including:

Optoelectropic Modules

- Optoelectronic Modules
- Hybrid/MCMs
 Microwave Products
 - Discrete Devices/Lasers





Semi-automatic and manual operation modes, individual bond parameter control, and capacity for a wide range of wire diameters allow easy use in ball bonding, ball bumping, coining, security bonding and single-point TAB applications.

4500 Series Ball Bonders

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Manual

Z Lever



Portable Dials Option

(4522 only)

4500 Series Ball Bonders

Digital/Analog Systems

Functional Comp	arison M	Model 4522	Model 4524AD

Modes of Operation

Full Manual Mode (Manual Z Control and Manual X-Y Positioning)

Semi-automatic Z Mode (Semi-automatic Z control and Manual X-Y)

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Semi-automatic Z & Auto-Stepback Mode (Semi-automatic Z and Auto-Stepback)

• Auto-2nd Bond Mode (Automatic Second Bond Cycle including Stepback)

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Multi-Process Capability

Ball Bonding, Bumping, Coining, Security Bonding, TAB*

Motorized Y Axis and Auto-Stepback

for controlled, highly repeatable wire length and loop formation

4500 Series Technical Specifications

Wire Diameter 0.7 mil (min) 18 μm (min)

3 mil (max) 76 µm (max)

Spool Size 2" 50.8 mm

Bonding Area 6" x 6" 152 mm x 152 mm

 Throat Depth
 5.6"
 143 mm

 Gross Table Motion
 5.5"
 140 mm

 Fine Table Motion
 0.55"
 14 mm

Mouse Ratio 6:1

"Z" Axis Movement

"Z" Axis Travel

Ultrasonic System

DC Servo w/ closed-loop control

0.360"

9.1 mm

high Q 60 kHz transducer

PLL ultrasonic generator

Low Ultrasonic Power 1.3 W High Ultrasonic Power 2.5 W

Bond Time

 Ball Bonding/Bumping Single Point TAB*
 10-200 ms

 20-1000 ms
 20-1000 ms

 Bond Force Force Coil
 10-160 g

 Wire Termination
 clamp/tear; adjustable tail

 Ball Formation System
 Negative Electronic Flame-Off

 Missing Ball System
 error indication and auto-stop

Temperature Controller up to 250° ± 0.5°C

Electrical Requirements 100-120/220-240 VAC, 50/60 Hz, 250 VA max.

Physical Dimensions 27" (680 mm) W x 27.5" (700 mm) D x 21" (530 mm) H

Weight

 Shipping
 122 lbs
 55 kg

 Net
 69 lbs
 31 kg

Options and Accessories

Single-Point TAB Kit w/ Programmable Z Axis

ESD Protection Kit

Portable Dials Kit (4522 Only)





For sales, service and manufacturing locations, visit:

www.kns.com

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